



100% Material Declaration Data Sheet for Spartan®-6 CS225 Package

PK648 (v1.0) April 4, 2014

Average Weight: 0.3908 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silver Epoxy					0.002453	0.628
	Silver	7440-22-4	77.50		0.001901	
	Bismaleimide monomer	Trade Secret	15.00		0.000368	
	Acrylate monomer	Trade Secret	7.50		0.000184	
Silicon Die					0.009301	2.380
	Silicon	7440-21-3	100		0.009301	
Gold Wire					0.005016	1.284
	Gold	7440-57-5	99.05		0.0049682	
	Palladium	7440-05-3	0.95		0.0000477	
	Calcium	7440-70-2	0.00		0.0000001	
Mold Compound					0.169166	43.287
	Solid Epoxy Resin	Trade Secret	5.00		0.008458	
	Phenol Resin	Trade Secret	4.50		0.007613	
	Fused Silica	60676-86-0	86.00		0.145483	
	Carbon Black	1333-86-4	0.50		0.000846	
	Metal Hydroxide	Trade Secret	4.00		0.006767	
Solder Ball					0.063453	16.237
	Tin	7440-31-5	63.00		0.039975	
	Lead	7439-92-1	37.00		0.023478	
Substrate					0.141411	36.185
	Gold	7440-57-5	1.37		0.001940	
	Nickel	7440-02-0	9.73		0.013764	
	Copper Foil	7440-50-8	22.47		0.031770	
	Copper Plating	7440-50-8	19.55		0.027652	
	Continuous Filament Fiber Glass	65997-17-3	16.05		0.022693	
	Non Halogen Fire Retardant	Trade Secret	2.47		0.003496	
	BT Core	105391-33-1 / 25722-66-1 / 9003-36-5 / 21645-51-2 / 7440-50-8	25.68		0.036309	
	Solder Mask	147-14-8 / 7727-43-7	2.68		0.003788	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
04/04/2014	1.0	Xilinx Initial Release

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